



PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

12-APR-2001

SUBJECT: Product/Process Change Notification #11162

TITLE: Replacement of selected Analog Microprocessor Reset Devices: MAX809LTR, MAX809STR

EFFECTIVE DATE: 19-Jul-2001

AFFECTED CHANGE CATEGORIES:

SUBCONTRACTOR FAB SITE
SUBCONTRACTOR TEST SITE
MARKING PROCESS
DESIGN CHANGE

AFFECTED PRODUCT DIVISION: Analog Products

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office.
or Don Warring <RRGA60@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office.
or Gilles Perez <FFGN8B@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact Sales Office or Marquita Jones <FFBPTW@onsemi.com>

DISCLAIMER:

Initial Product/Process Change Notification (IPCN) -First Notification distributed to customers.
Distributed at least 120 days from the effective date of the change.

Final Product/Process Change Notification (FPCN) - Final Notification completing the notification process. Distributed at least 60 days from the effective date of the change. ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

Product/Process Change Notification #11162

**DESCRIPTION AND PURPOSE**

ON Semiconductor wishes to announce the redesign and manufacturing site change of the MAX809LTR and MAX809STR devices. Parametric performance is unchanged with the exception of supply current and maximum transient duration, both of which are improved in the redesigned versions. There are no functional changes or specification changes other than the improvements in supply current and maximum transient duration. The redesigned devices will be fabricated at our ON Aizu-6 facility in Aizu, Japan and assembly and final test will be done at ON's Seremban, Malaysia facility. Both the ON Aizu-6 and Seremban sites have been QS9000 certified. ON Semiconductor will provide modified datasheets, samples, and reliability reports for the redesigned devices upon request. Please contact your ON Sales representative or the personnel listed on this notification if there is any additional information or technical support required to transition to the redesigned devices. Production will be converted to the redesigned devices upon expiration of this notification.

Redesigned material can be distinguished by the marking scheme:

MAX809LTR (OLD Device):J1
MAX809LTR (Redesigned Device):SPW
MAX809STR (OLD Device):J4
MAX809STR (Redesigned Device):SPT

QUALIFICATION PLAN: Available upon request.

RELIABILITY DATA SUMMARY: Available upon request.

ELECTRICAL CHARACTERISTIC SUMMARY:**Old device:**

<u>Supply Current</u>	<u>Typical(uA)</u>	<u>Max (uA)</u>
MAX809LTR: V _{CC} < 5.5 V	24	60
MAX809STR: V _{CC} < 3.6 V	17	50

New Device:

<u>Supply Current</u>	<u>Typical(uA)</u>	<u>Max (uA)</u>
V _{CC} = 3.3 V		
T A = -40DegC to +85DegC	0.5	1.2
T A = 85DegC to +105DegC		2.0
V _{CC} = 5.5 V	<u>Typical(uA)</u>	<u>Max (uA)</u>
T A = -40DegC to +85DegC	0.8	1.8
T A = 85DegC to +105DegC		2.5

Old device:

V_{CC} to Reset Delay V_{CC} = V_{TH} to (V_{TH} - 100 mV): 20usec

New device:

V_{CC} to Reset Delay V_{CC} = V_{TH} to (V_{TH} - 100 mV): 10usec

CHANGED PART IDENTIFICATION:

Marking will change. The current marking for the MAX809LTR is "J1". The new marking for MAX809LTR will be "SPW". The current marking for the MAX809STR is "J4". The new marking for MAX809STR will be "SPT".

AFFECTED DEVICE LIST:**PART**

MAX809LTR
MAX809STR